Customized Die Bonding Solutions with Swiss Precision

Tresky Corporation
704 Ginesi Drive, Suite 11A
Morganville, NJ 07751
Phone: 732-536-8600
Fax: 732-810-0433

www.tresky.com

About Tresky

- Manufacture Customized Die Attach, Flip Chip Bonding and Sorting Systems
- Founded in 1980
- Over 1200+ Systems installed worldwide
- Offices
  - Tresky AG - Headquarters
    Thalwil, Switzerland
  - Tresky Germany
    Berlin, Germany
  - Tresky USA
    Morganville, NJ

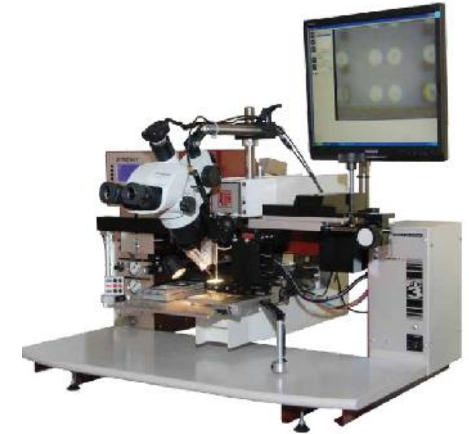
TRESKY

From R&D to Production

T-3000/2 M
Manual XY with Manual Z
Top Down or Flip Chip
Alignment

T-3000/2 FC3
Manual XY with Auto Z
Top Down or Flip Chip
Alignment

T-4909
Manual Top Down
Alignment



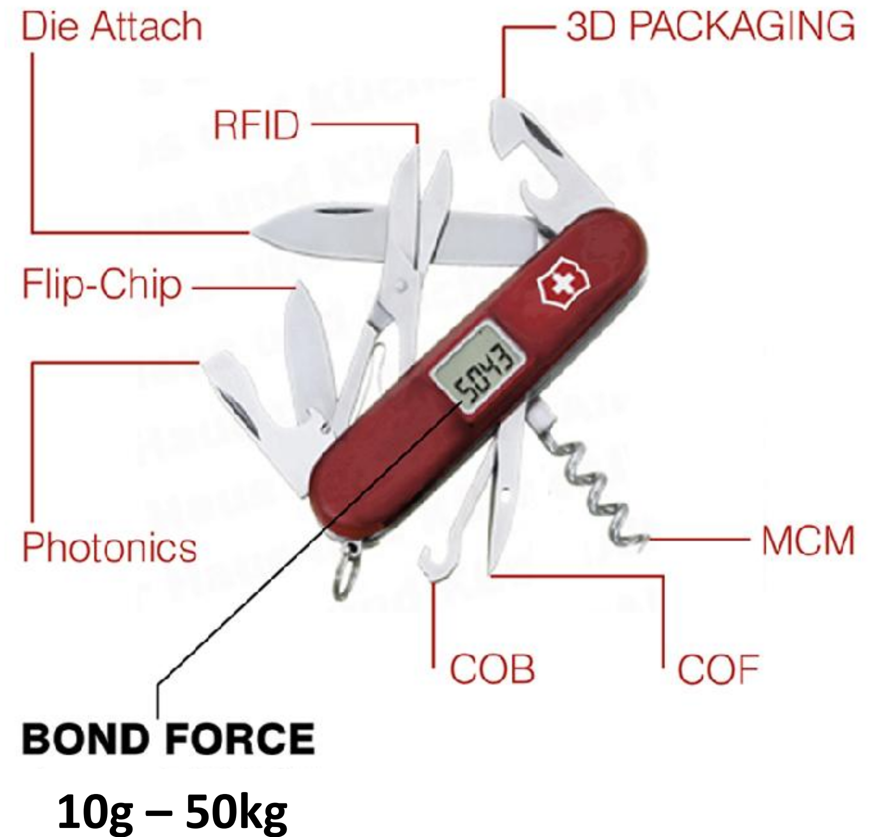
T-3000FC3-HF
Manual XY with Auto Z
Top Down or Flip Chip
Alignment
Force Up to 50kg

T-6000-L
Fully-Automated
8µm @ 3sigma

T-8000
Fully-Automated
5µm @ 3 sigma

Advantages

- Versatility
- Upgradeable
- Accuracy and Repeatability
- True Vertical Technology™
- Simple, User-friendly



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T-3000/2-FC3

Semi-Automated Flip Chip Eutectic Die Bonding System

- Z axis with 1µm resolution
- 1g Bond Force Control
- Alignment Resolution: 0.5µm
- Placement Area: 220 x 220mm
- Pick from up to 8inch wafer
- Bond Force: 15g – 400g
- Beamsplitter with Live Images
- Adjustable Optics for varying thickness samples

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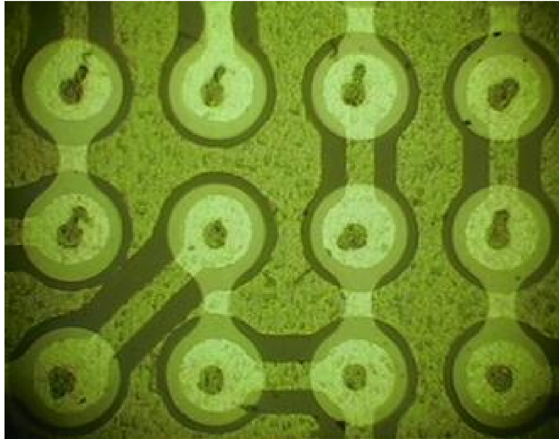
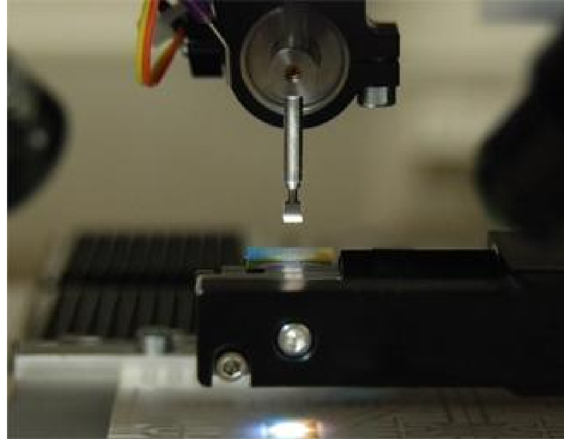
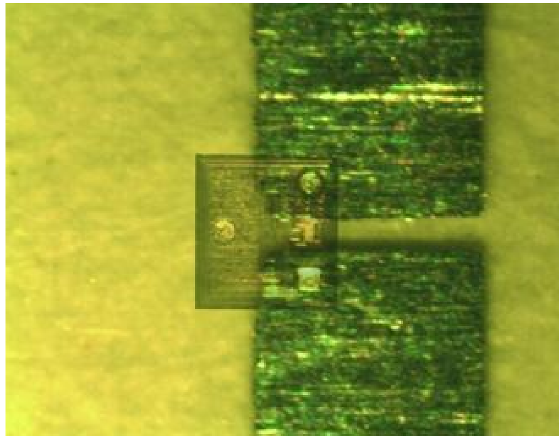
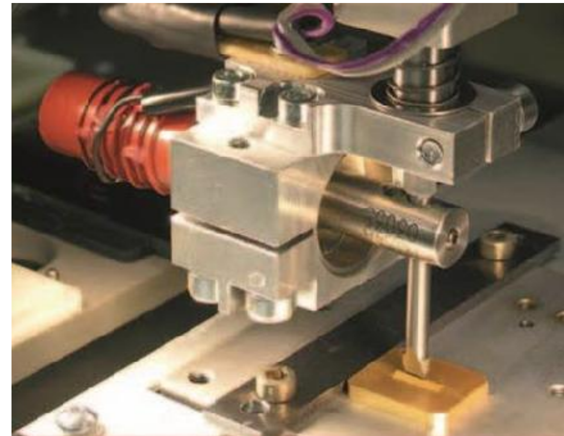
T-3000/2-FC3 Applications









- Eutectic Bonding
- Epoxy Bonding
- Thermocompression
- Ultrasonic/Thermosonic
- Flip Chip/2.5/3D
- Stamping/Flux Dipping
- Surface Mount
- Sorting

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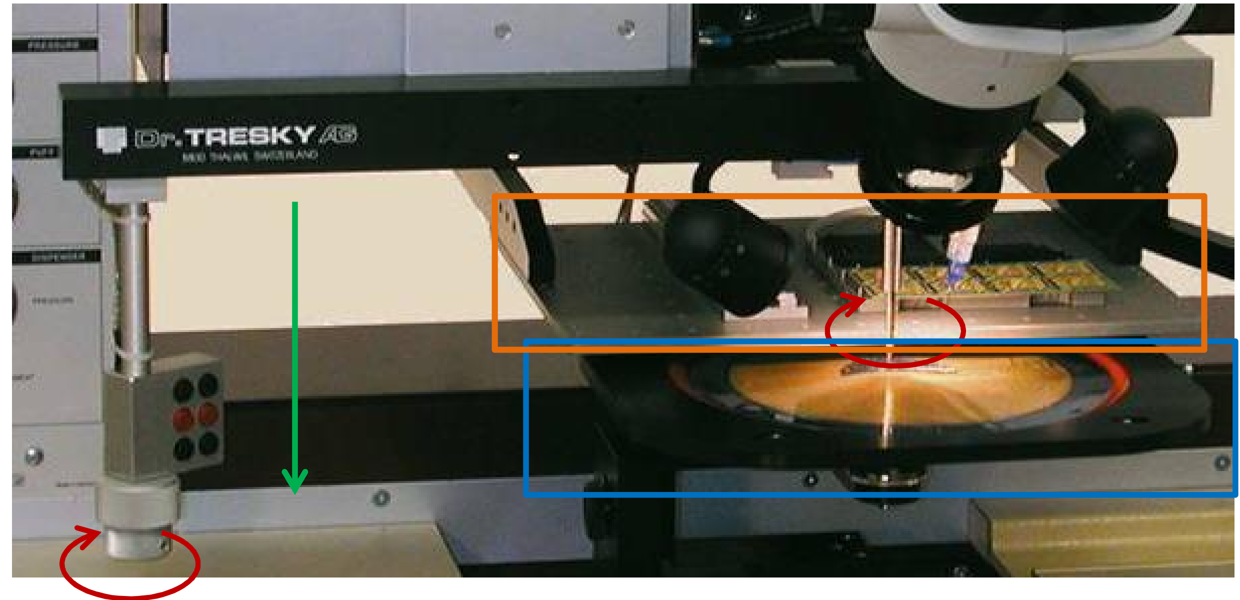
T-3000/2-FC3 Differentiators

- Bonding Arm only has Z motion - True Vertical Technology™
- 360˚ Theta control of spindle
- XY Alignment performed by table
- Pick from Wafer using patented die ejector



- Capable of multiple processes without changeover

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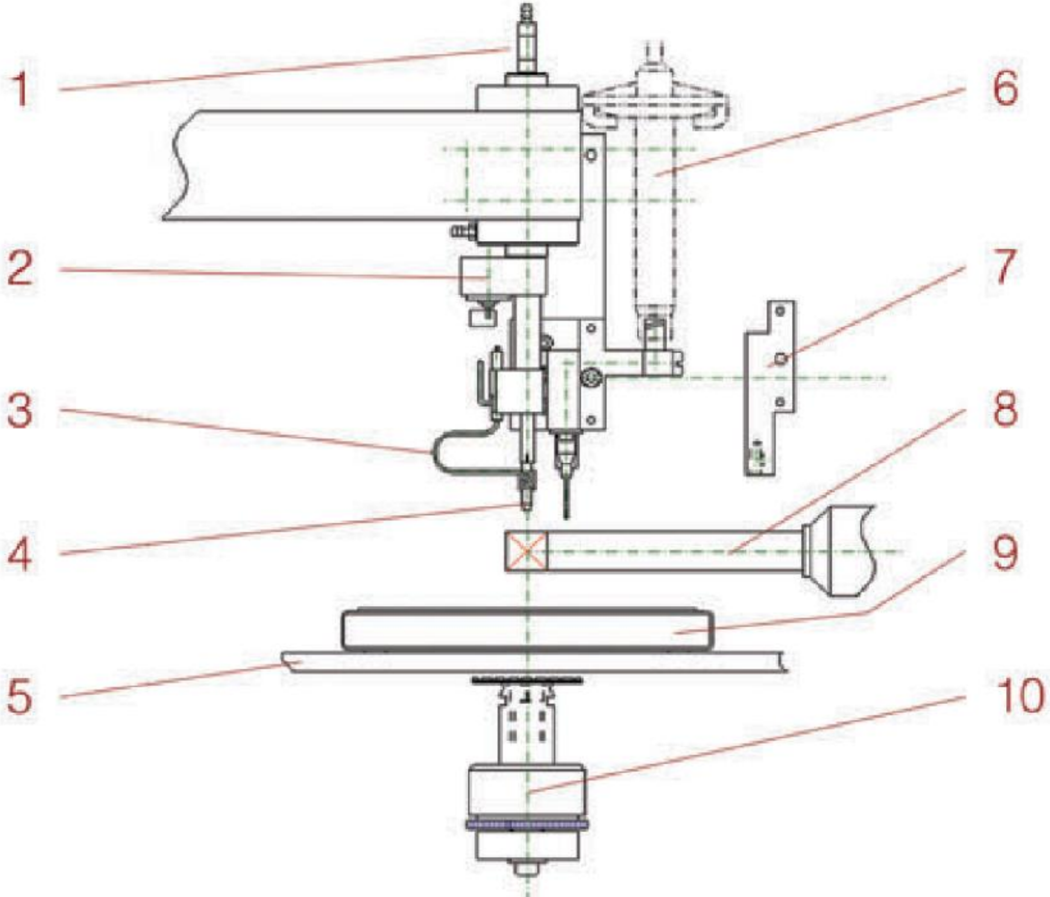
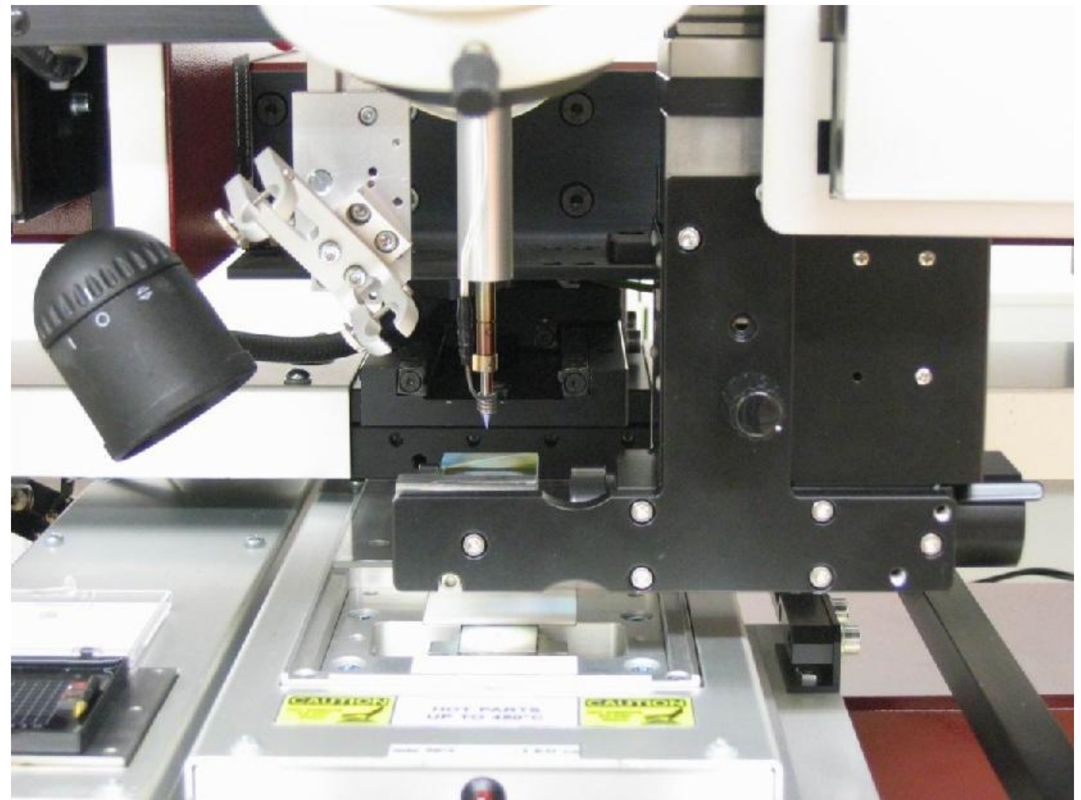
Tresky True Vertical Technology™



Tresky True Vertical Technology™

- True Vertical Technology™
- Beam Splitter with Zoom Optics and Camera enabling a simultaneous view of the substrate and chip
- 0.5µm alignment resolution
- LED illumination (Top and Bottom) and Coaxial illumination
- 23X optical zoom camera
- FOV 0.3 to 6.5mm
- Multiple Point Alignment available
- Motorized fixed point engagement or Multiple point movement



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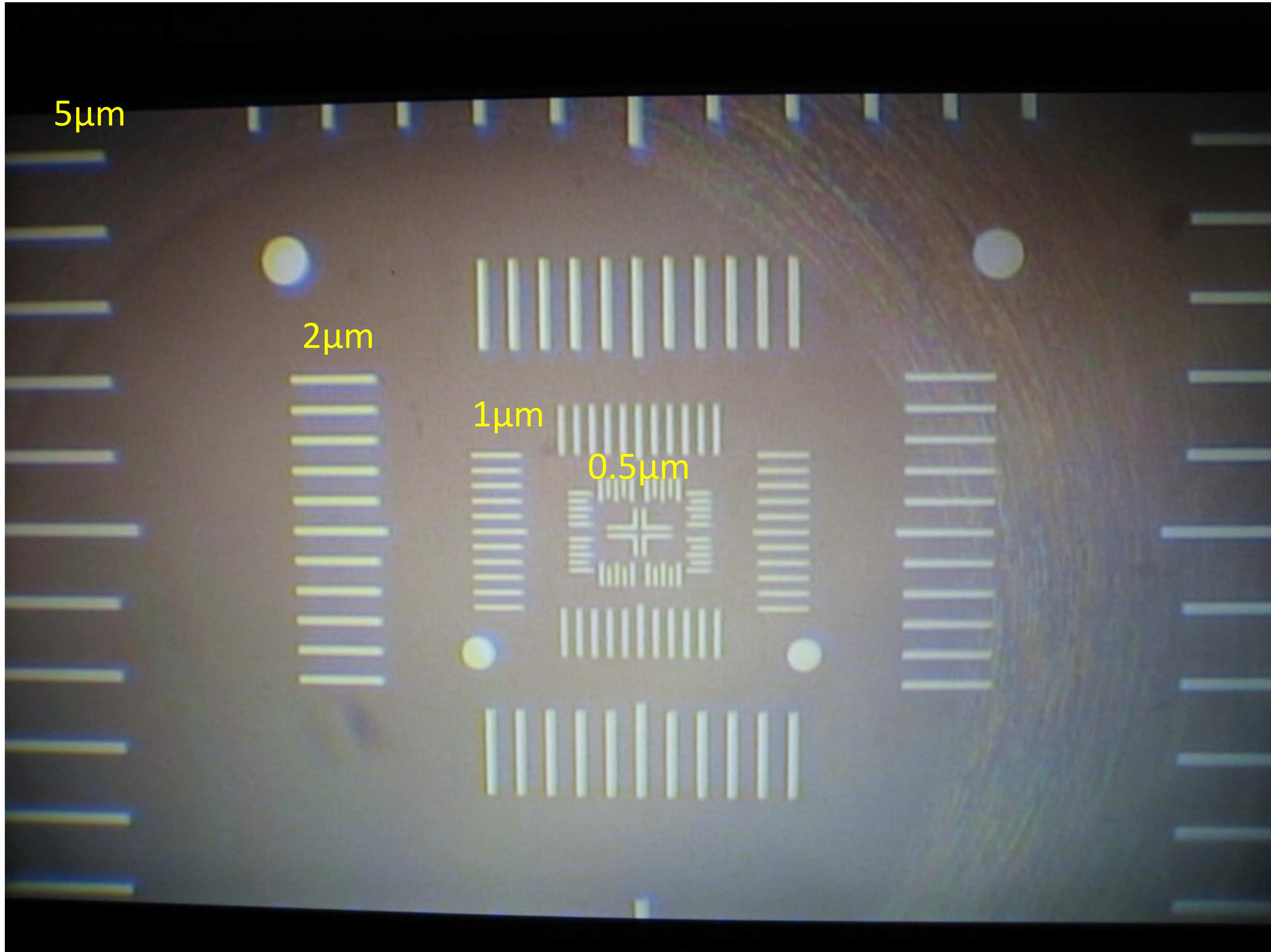
Tresky Flip Chip Optics



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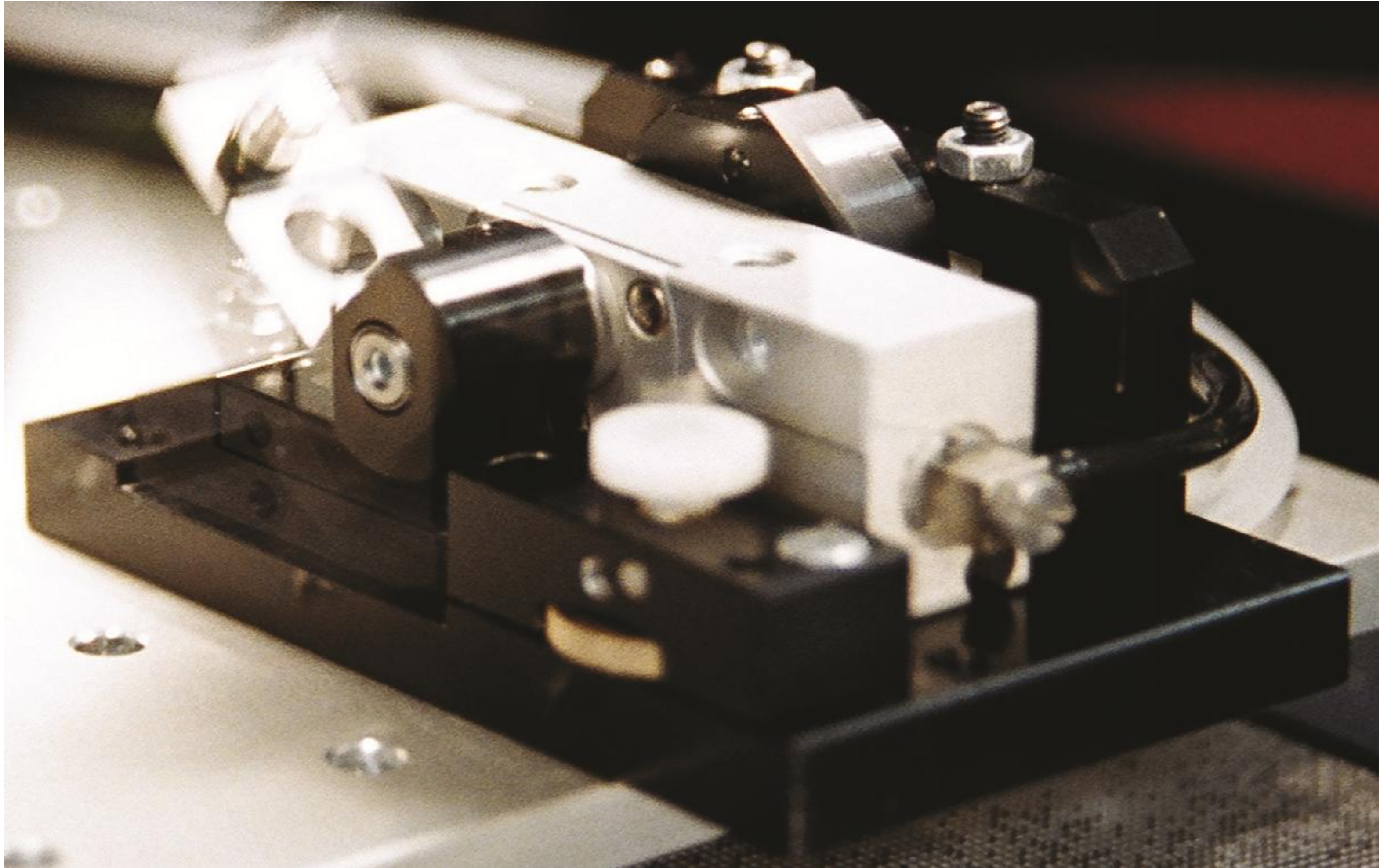
Tresky Chip Flipper



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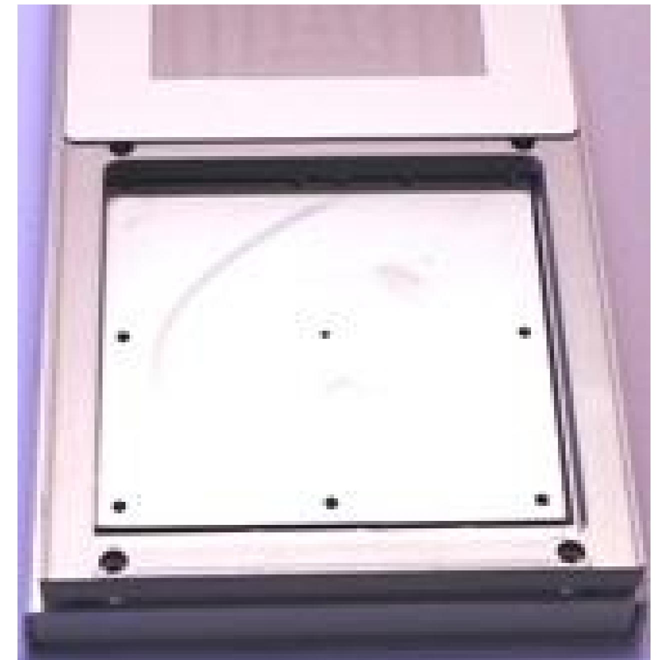
Tresky Eutectic Bonding

- 20x20 mm Programmable Heating Plate
  - 400C max; 18C/sec
  - Integrated Cooling
  - Inert Gas Chamber available
- 52 x 52 mm Programmable Heating Plate
  - 400C max; 30C/sec
  - Integrated Cooling
  - Inert Gas Blanket available
- 100 x 100 mm Programmable Heating
  - 400C max; 25C/sec
  - Integrated Cooling
  - Inert Gas Chamber Available
- Static Heating Plates Available



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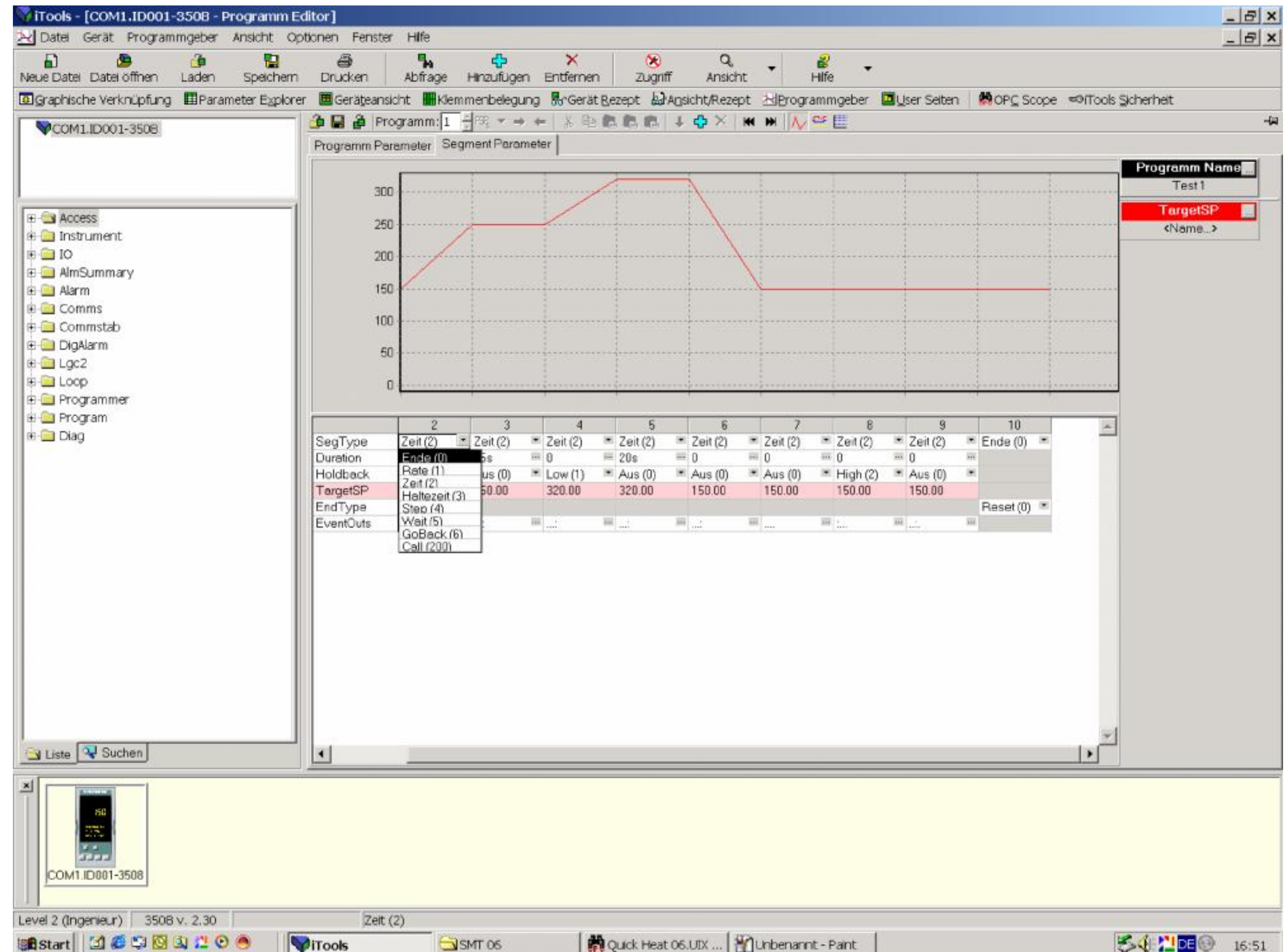
Tresky Eutectic Programming via iTools

- Program
  - Temperatures
  - Ramp rates
  - Dwell times
  - Forming gas
- Watch it as it happens



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T-3000/2-FC3 Summary

- Accurate
- Repeatable
- Versatile
- R&D to Low Volume Production
- Easy to Use
- Full Range Bond Force
- Multiple Applications
- Low cost of ownership

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